

Title (en)  
NICKEL PLATING SOLUTION

Title (de)  
NICKELPLATTIERUNGSLÖSUNG

Title (fr)  
SOLUTION DE PLACAGE DE NICKEL

Publication  
**EP 3312308 A1 20180425 (EN)**

Application  
**EP 17197736 A 20171023**

Priority  
JP 2016208151 A 20161024

Abstract (en)  
The present invention relates to a boric-acid free nickel plating composition which does not include organic carboxylic acid but has high bath-pH-stability. The nickel plating composition provides a nickel plating film suitable for the use of electronic components.

IPC 8 full level  
**C25D 3/12** (2006.01); **C25D 7/12** (2006.01)

CPC (source: CN EP KR US)  
**C25D 3/12** (2013.01 - CN EP KR US); **C25D 7/123** (2013.01 - CN EP KR US)

Citation (applicant)  

- JP 2012126951 A 20120705 - MELTEX INC
- JP 2004265253 A 20040924 - MATSUSHITA ELECTRIC WORKS LTD
- JP 2001172790 A 20010626 - TOKYO METROPOLITAN GOV
- JP 2010267208 A 20101125 - IRF KK, et al

Citation (search report)  

- [X] JP 2008285732 A 20081127 - MELTEX INC
- [XDI] JP 2012126951 A 20120705 - MELTEX INC

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TW 201816191 A 20180501; US 2018112319 A1 20180426

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**EP 17197736 A 20171023**; CN 201710963553 A 20171017; JP 2016208151 A 20161024; KR 20170137321 A 20171023;  
TW 106134778 A 20171011; US 201715692521 A 20170831